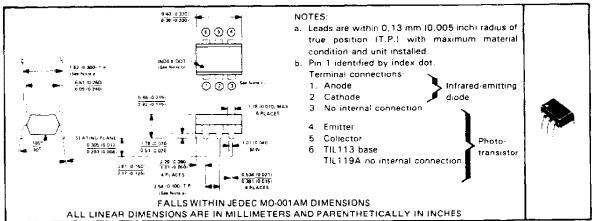
- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Darlington-Connected Phototransistor
- High Direct-Current Transfer Ratio . . . 300% Minimum at 10 mA
- High-Voltage Electrical Isolation . . . 1500-Volt Rating
- Plastic Dual-In-Line Package
- Base Lead Provided on TIL113 for Conventional Transistor Biasing
- No Base Lead Connection on TIL 119A for High-EMI Environments
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon darlington-connected photo-transistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage
Collector Base Voltage (TIL113)
Collector-Emitter Voltage (See Note 1)
Emitter-Collector Voltage
Emitter-Base Voltage (TIL113)
Input-Diode Reverse Voltage
Input-Diode Continuous Forward Current at (or below) 25°C Free-Air Temperature (See Note 2) 100 mA
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:
Infrared-Emitting Diode (See Note 3)
Phototransistor (See Note 4)
Total (Infrared-Emitting Diode plus Phototransistor, See Note 5)
Storage Temperature Range
Lead Temperature 1,6 mm (1/16 Inch) from Case for 10 Seconds

NOTES 1. This value applies when the base emitter diode is open circuited

- 2. Derate linearly to 100°C free air temperature at the rate of 1.33 mA. C
- 3. Denate linearly to 100 C free air temperature at the rate of 2 mW/ C.
- 4. Denote linearly to 100°C free air temperature at the rate of 2 mW/ C
- 5. Denate linearly to 100°C free-air temperature at the rate of 3.33 mW/ C



TIL113, TIL119A OPTOCOUPLERS

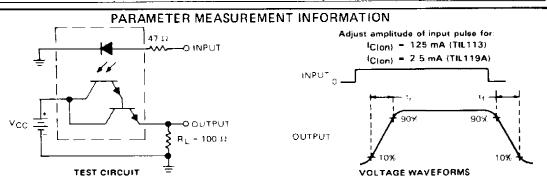
electrical characteristics at 25°C free-air temperature

PARAMETER		TEST CONDITIONS [†]				TIL 113		TIL119A			UNIT
					MIN TYP		MAX	MIN	TYP	MAX	UNIT
V(BR)CBO	Collector Base Breakdown Voltage	i _C = 10 μA.	ι _Ε - 0,	1 _F - 0	30						V
V(BR)CEO	Collector-Emitter Breakdown Voltage	I _C ÷ 1 mA.	+B = 0'	IF - 0	30			30			V
V(BR)EBO	Emitter-Base Breakdown Voltage	IE = 10 μA,	IC 0,	1 _F - 0	7						V
V(BR)ECO	Emitter-Collector Breakdown Voltage	le = 10 μA.	lt = 0					7			٧
1	On State	V _{CE} = 1 V.	ig : 0,	1 _F = 10 mA	30	100		İ			mA
¹ C(pn)	Collector Current	V _{CE} = 1 V.	I _F = 10 mA					30	160	_]
^I C(off)	Off-State Collector Current	V _{CE} = 10 V.	IB - 0'	1 _F - 0	i		100			100	пA
pEE	Transistor Static Forward Current Transfer Ratio	V _{CE} - 1 V,	I _C - 10 mA.	le = 0		15,000					
v _F	Input Diode Static Forward Voltage	1p = 10 mA					1.5			1.5	V
VCE (sat)	Collector-Emitter Saturation Voltage	I _C = 125 mA, I _C = 30 mA,	lg = 0, lp = 10 mA	l _F = 50 mA			1.2			1	V
110	Input-to-Output Internal Resistance	V _{in-out} = +1.5 kV	, See Note 6		1011			1011			7.1
C ₁₀	Input-to-Output Capacitance	V _{in out} 10,	f= 1 MHz.	See Note 6		1	13	1	1	1.3	pF

NOTE 6: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together. *Reference to the base are not applicable to Til.119A.

switching characteristics at 25 C free-air temperature

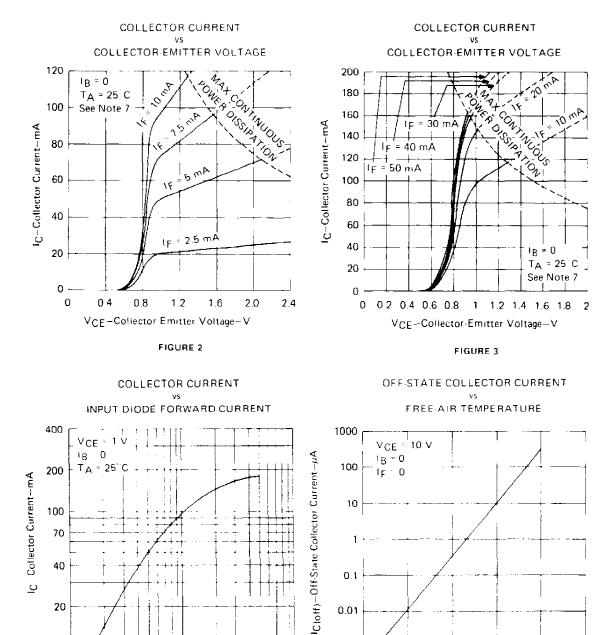
	PARAMETER	TEST CONDITIONS		TL113			1	UNIT		
		15	21 CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
ī,	Rise Time	V _{CC} - 15 V.	Iclon) = 125 mA,		300					
f	Fall Time	R _L = 100 Ω,	See Figure 1		300					μS
r	Rise Time	V _{CC} = 10 V.	I _{C(on)} = 2.5 mA,					300		T.,
f	Fall Time		See Figure 1					300		448



- NOTES: a The input waveform is supplied by a generator with the following characteristics: $Z_{out} = 50 \Omega_c t_f \approx 15 \text{ ns. duty cycle} \approx 1\%$.
 - $t_W=500~\mu s$. b. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r \lesssim 12~\text{ns},~R_{10} \approx 1~\text{M}\Omega,~C_{10} \lesssim 20~\text{pF}$

FIGURE 1-SWITCHING TIMES

TYPICAL CHARACTERISTICS



NOTE 7. Pulse operation of input diode is required for operation beyond limits shown by dotted line.

20

10 Ip-Forward Current-mA

FIGURE 4

40

70 100

10



0.001

0

75

100

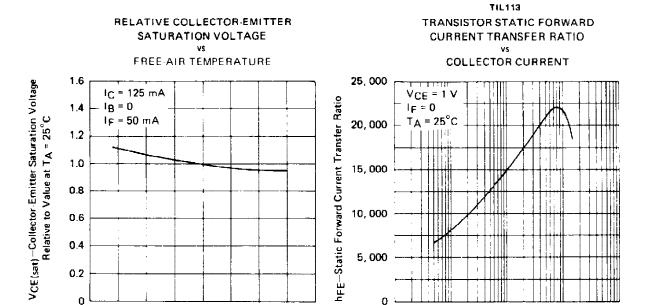
125

50

TA-Free-Air Temperature- C

FIGURE 5

TYPICAL CHARACTERISTICS



0.1

0.4

75 100 125

FIGURE 6

25 50

TA-Free-Air Temperature-°C

0

-75 -50 -25

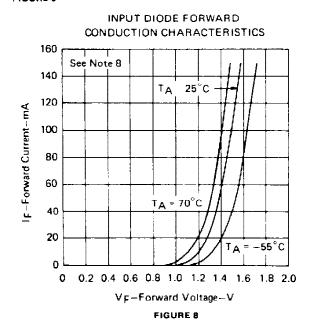
FIGURE 7

10

IC-Collector Current-mA

40 100

400 1000



NOTE B: This parameter was massured using pulse techniques, $t_{\rm W}$ = 1 ms, duty cycle \leq 2%.

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